

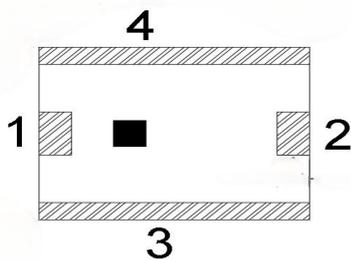
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

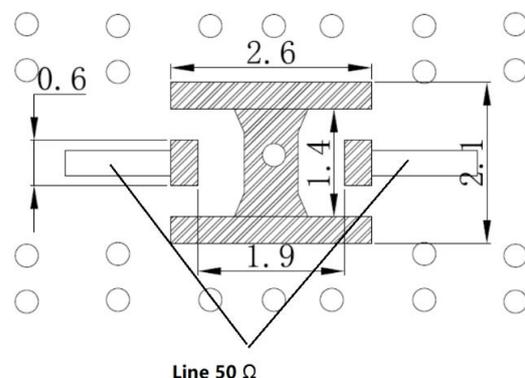
NO.	Parameter	SPC
1	Frequency (MHz)	2400~2500
2	Insertion Loss (dB)@25°C	≤1.2
3	Ripple (dB)	≤0.6
4	VSWR(In BW)	≤2.0
5	Attenuation	≥30dB@880~1785MHz
		≥35dB@1850~1910MHz
		≥25dB@4800~5000MHz
		≥22dB@7200~7500MHz
6	In/Output Impedance (Ω)	50
<b>Operating &amp; Storage Condition (Component)</b>		
Operation Temperature Range: -55°C ~ +85°C		
Storage Temperature Range: -55°C~ +85°C		
<b>Storage Condition before Soldering (Included packaging material)</b>		
Storage Temperature Range: +5 ~ +40 °C		
Humidity: 30 to 70% relative humidity		

### Construction



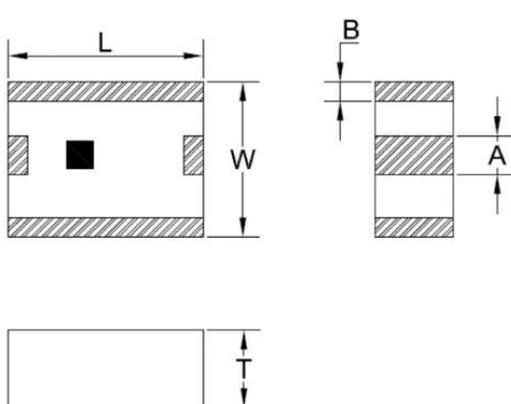
PIN	Connection	PIN	Connection
1	input Port	2	output Port
3	GND	4	GND

### Mounting Considerations

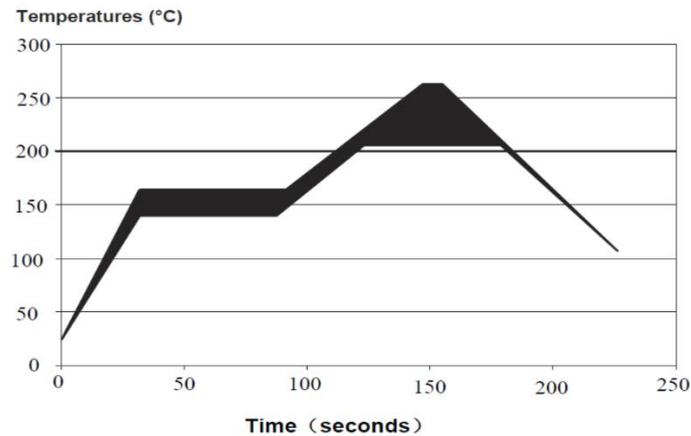


Unit: mm

### Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.50±0.10
	B	0.20±0.10

### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.